

MP62340-1/MP62341-1

3.3V/5V, Dual-Channel 1A

Current-Limited Power Distribution Switches with Output Discharge

DESCRIPTION

The MP62340-1/MP62341-1 Power Distribution Switch features internal current limiting to prevent damage to host devices due to faulty load conditions. The MP62340-1/MP62341-1 analog switch has $85m\Omega$ on-resistance and operates from 2.7V to 5.5V input. It is available with guaranteed current limits, making it ideal for load switching applications. The MP62340-1/MP62341-1 has built-in protection for both over current and increased thermal stress. For over current, the device will limit the current by changing to a constant current mode.

As the temperature increases as a result of short circuit, then the device will shut off. The device will recover once the device temperature reduces to approx 120°C.

The MP62340-1/MP62341-1 involves discharge function that provides a resistive discharge path for the external output capacitor when the part is disabled.

The MP62340-1/MP62341-1 is available in 8-pin MSOP package with exposed pad and SOIC package without exposed pad.

FEATURES

- 1A Continuous Current.
- Accurate Current Limit
- Output Discharge Function
- 2.7V to 5.5V Supply Range
- 140µA Quiescent Current
- 85mΩ MOSFET
- Thermal-Shutdown Protection
- Under-Voltage Lockout
- 8ms FLAG Deglitch Time
- No FLAG Glitch During Power Up
- Reverse Current Blocking
- Active High & Active Low Options
- UL Recognized: E322138

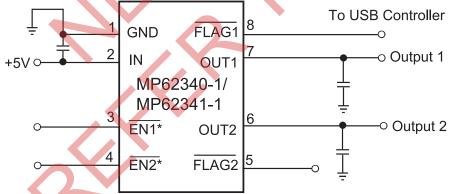
APPLICATIONS

- PDAs
- Portable GPS
- Notebook PC
- Set-top-box
- Telecom and Network Systems
- PC Card Hot Swap
- USB Power Distribution

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TYPICAL APPLICATION



EN is active high for MP62341-1

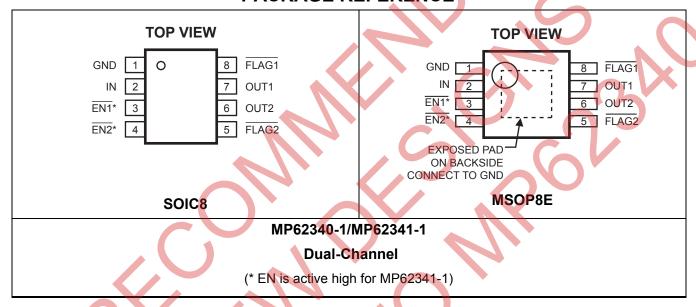


ORDERING INFORMATION

Part Number	Enable	Switch	Maximum Continuous Load Current	Typical Short- Circuit Current @ T _A =25C	Package	Top Marking	Temperature
MP62340DS-1*	Active				SOIC8	M62340-1	
MP62340DH-1	Low	Dual	1A	1.5A	MSOP8E	623 <u>40</u>	–40°C to +85°C
MP62341DS-1	Active				SOIC8	M62341-1	-40 C to 103 C
MP62341DH-1	High				MSOP8E	623 <u>41</u>	

* For Tape & Reel, add suffix –Z (e.g. MP62340DS–1–Z). For RoHS compliant packaging, add suffix –LF (e.g. MP62340DS–1–LF–Z)

PACKAGE REFERENCE



ABSOLUTE MAXIMUM RATINGS (1)

IN	0.3V to +6.0V
EN, FLAG, OUT to GND	0.3V to +6.0V
Continuous Power Dissipation ($TA = +25^{\circ}C)^{(2)}$
MSOP8E	2.3W
SOIC8	1.4W
Junction Temperature	150°C
Lead Temperature	260°C
Storage Temperature	
Operating Temperature	_40°C to +85°C

Thermal Resistance (3)	$oldsymbol{ heta}_{JA}$	$oldsymbol{ heta}_{JC}$	
SOIC8	90	42	.°C/W
MSOP8E	55	12	.°C/W

Notes

- 1) Exceeding these ratings may damage the device.
- 2) The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-to ambient thermal resistance θ_{JA_i} and the ambient temperature T_A . The maximum allowable continuous power dissipation at any ambient temperature is calculated by PD (MAX) = $(T_J (MAX) T_A)/\theta_{JA}$. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 3) Measured on JESD51-7, 4-layer PCB.

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ELECTRICAL CHARACTERISTICS (4)

V_{IN}=5V, T_A=+25°C, unless otherwise noted.

Parameter	Condition		Тур	Max	Units
IN Voltage Range		2.7		5.5	V
Supply Current	One Channel Enabled, I _{OUT} =0, One Switch ON		90	120	μΑ
Supply Current	Both Channels Enabled, I _{OUT} =0, Both Switches ON		140	160	μΑ
Shutdown Current	Device Disable, V _{OUT} =float, V _{IN} =5.5V		1		μA
Off Switch Leakage	Device Disable, V _{IN} =5.5V		1		μΑ
Current Limit			1.5	2.2	Α
Trip Current	Current Ramp (slew rate≤100A/s) on Output		1.7	2.4	Α
Under-voltage Lockout	Rising Edge	1.95		2.65	V
Under-voltage Hysteresis			250		mV
FET On Resistance	I _{OUT} =100mA (-40°C≤T _A ≤+85°C)		85	130	mΩ
EN Input Logic High Voltage		2			V
EN Input Logic Low Voltage				0.8	V
FLAG Output Logic Low Voltage	I _{SINK} =5mA			0.4	V
FLAG Output High Leakage Current	V _{IN} =V _{FLAG} =5.5V			1	μА
Thermal Shutdown			140		°C
Thermal Shutdown Hysteresis			20		°C
V _{OUT} Rising Time, Tr ⁽⁵⁾	$V_{\rm IN}$ =5.5V, $C_{\rm L}$ =1 μ F, $R_{\rm L}$ =5.5 Ω		0.9		ms
(6)	V_{IN} =2.7V, C_L =1 μ F, R_L =5.5 Ω V_{IN} =5.5V, C_L =1 μ F, R_L =5.5 Ω		1.7	0.5	ms ms
V _{OUT} Falling Time, Tf ⁽⁶⁾	$V_{IN} = 2.7V$, $C_L = 1\mu F$, $R_L = 5.5\Omega$			0.5	ms
Turn On Time, Ton (7)	$C_L=100\mu F$, $RL=5.5\Omega$			3	ms
Turn Off Time, Toff (8)	$C_L=100\mu F$, $RL=5.5\Omega$			10	ms
Discharge Resistance			100		Ω
FLAG Deglitch Time	,		8	15	ms
EN Input Leakage			1		μΑ
Reverse Leakage Current	V _{OUT} =5.5V, V _{IN} =GND		0.2		μA

Notes:

- 4) Production test at +25°C. Specifications over the temperature range are guaranteed by design and characterization.
- Measured from 10% to 90% output signal. Measured from 90% to 10% output signal.
- Measured from 50% EN signal to 90% output signal.
- Measured from 50% EN signal to 10% output signal.



PIN FUNCTIONS

SOIC8 MSOP8E	Name	Description
1	GND, Exposed Pad (MSOP8E)	Ground. MSOP8E exposed pad must be connected to a ground plane for optional thermal performance.
2	IN	Input Voltage. Accepts 2.7V to 5.5V input.
3	EN1	Active Low: (MP62340-1), Active High: (MP62341-1)
4	EN2	Active Low: (MP62340-1), Active High: (MP62341-1)
5	FLAG2	IN-to-OUT2 Over-current, active-low output flag. Open-Drain.
6	OUT2	IN-to-OUT2 Power-Distribution Switch Output.
7	OUT1	IN-to-OUT1 Power-Distribution Switch Output
8	FLAG1	IN-to-OUT1 Over-current, active-low output flag. Open-Drain.

TYPICAL PERFORMANCE CHARACTERISTICS



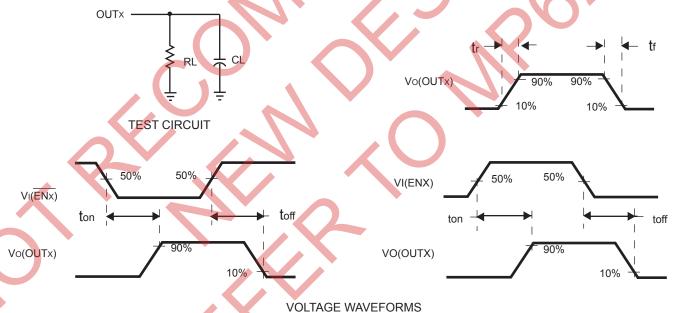
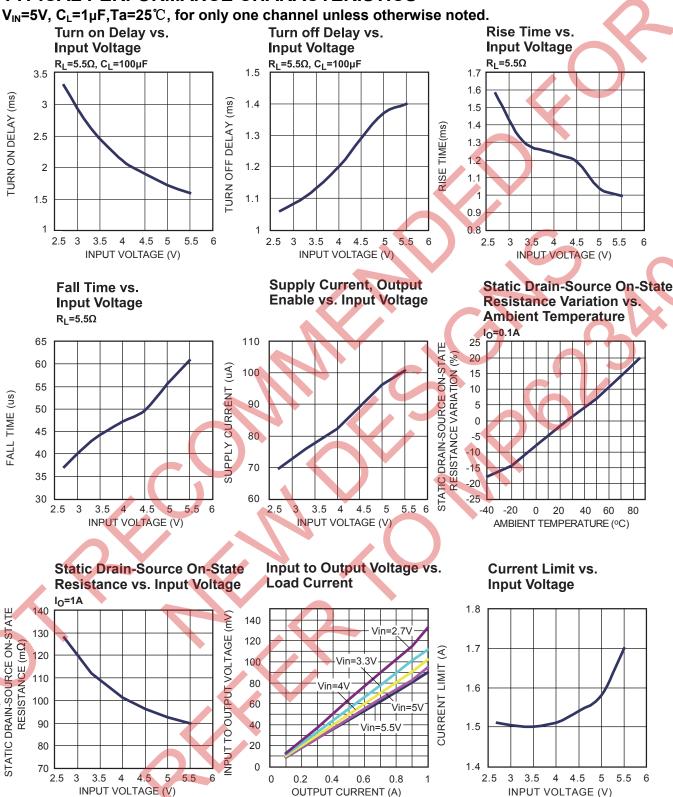


Figure 1—Test Circuit and Voltage Waveforms



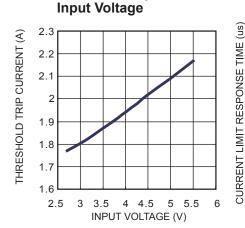
TYPICAL PERFORMANCE CHARACTERISTICS





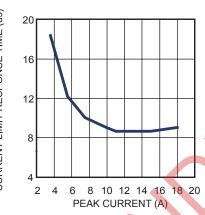
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 V_{IN} =5V, C_L =1 μ F, Ta=25 $^{\circ}$ C, for only one channel, unless otherwise noted.



Threshold Trip Current vs.

Current Limit Response Time vs. Peak Current



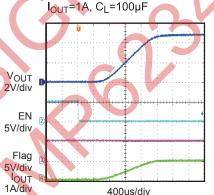
Turn On Delay and Rise Time with 1µF Load

I_{OUT}=1A V_{OUT} 5V/div ΕN 5V/div Flag 5V/div I_{OUT} 1A/div 400us/div

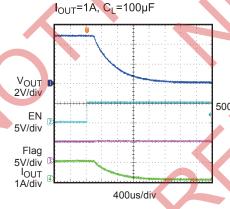
Turn Off Delay and Fall Time with 1µF Load



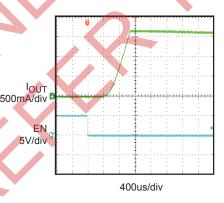
Turn On Delay and Rise Time with 100uF Load



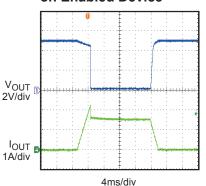
Turn Off Delay and Fall Time with 100µF Load



Short Circuit Current, Device Enabled into Short



Threshold Trip Current with Ramped Load on Enabled Device

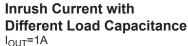




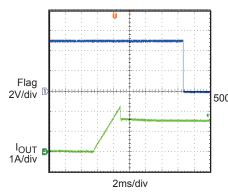
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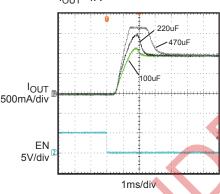
 V_{IN} =5V, C_L =1 μF ,Ta=25 $^{\circ}C$, for only one channel, unless otherwise noted.

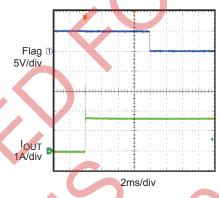
Ramped Load on Enabled Device





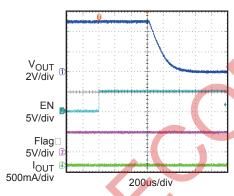






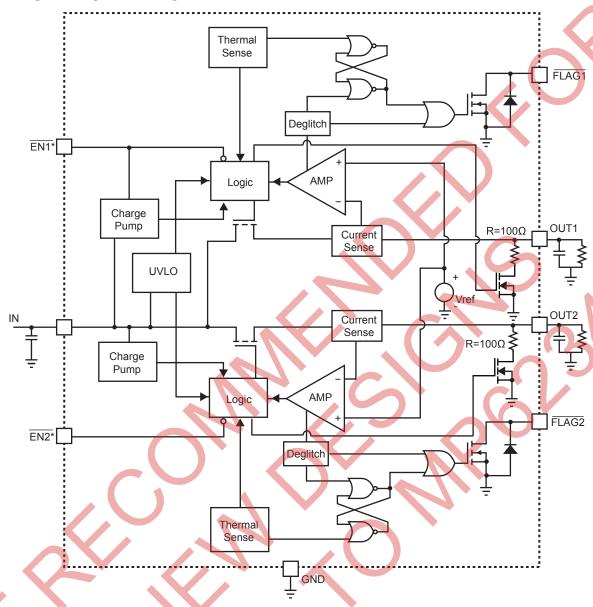
Turn Off Delay and Fall Time with Output Discharge

I_{OUT}=0A





FUNCTION BLOCK DIAGRAM



* EN is active high for MP62341-1

Figure 2—Functional Block Diagram



DETAILED DESCRIPTION

Over Current

When the load exceeds trip current (minimum threshold current triggering constant-current mode) or a short is present, MP62340-1/MP62341-1 switches into to a constant-current mode (current limit value). MP62340-1/MP62341-1 will be shutdown only if the over current condition stays long enough to trigger thermal protection.

Trigger over current protection for different overload conditions occurring in applications:

- The output has been shorted or overloaded before the device is enabled or input applied. MP62340-1/MP62341-1 detects the short or overload and immediately switches into a constant-current mode.
- 2) A short or an overload occurs after the device is enabled. After the current-limit circuit has been tripped (reached the trip current threshold), the device switches into constantcurrent mode. However, high current may flow for a short period of time before the current-limit circuit can react.
- 3) Output current has been gradually increased beyond the recommended operating current. The load current rises until the trip current threshold is reached or until the thermal limit of the device is exceeded. The MP62340-1/MP62341-1 is capable of delivering current up to the trip current threshold without damaging the device. Once the trip threshold has been reached, the device switches into its constant-current mode.

Flag Response

The FLAG pin is an open drain configuration. This FAULT will report a fail mode after an 8ms deglitch timeout. This is used to ensure that no false fault signals are reported. This internal deglitch circuit eliminates the need for extend components. The FLAG pin is not deglitched during an over temp or voltage lockout.

Thermal Protection

The purpose of thermal protection is to prevent damage in the IC by allowing exceptive current to flow and heating the junction. The die temp. is internally monitored until the thermal limit is reached. Once this temp. is reached, the switch will turn off and allow the chip to cool. The switch has a built-in hysteresis.

Under-voltage Lockout (UVLO)

This circuit is used to monitor the input voltage to ensure that the MP62340-1/MP62341-1 is operating correctly. This UVLO circuit also ensures that there is no operation until the input voltage reaches the minimum spec.

Enable

The logic pin disables the chip to reduce the supply current. The device will operate once the enable signal reaches the appropriate level. The input is compatible with both COMS and TTL.

Output Discharge

The part involves a discharge function that provides a resistive discharge path for the external output capacitor. The function will be active when the part is disabled (Input voltage is under UVLO or enable is deasserted) and it will be done in a very limited time.



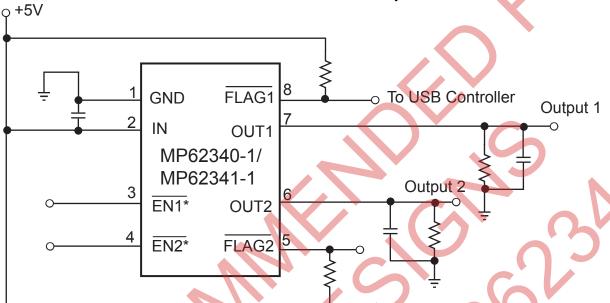
APPLICATION INFORMATION

Power-Supply Considerations

Greater than $10\mu F$ capacitor between IN and GND is recommended. This precaution reduces power-supply transients that may cause ringing

on the input and improves the immunity of the device to short-circuit transients.

In order to achieve smaller output load transient, placing a high-value electrolytic capacitor on the output pin(s) is recommended when the output load is heavy.



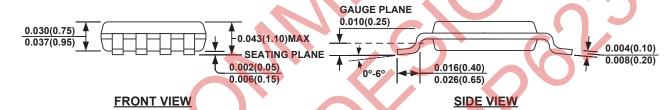
*EN is active high for MP62341-1
Figure 3—Application Circuit

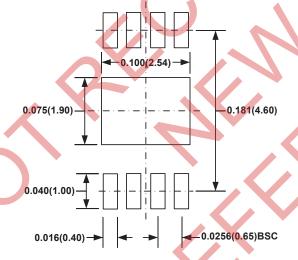
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PACKAGE INFORMATION

MSOP8E (EXPOSED PAD) 0.114(2.90) 0.087(2.20) 0.099(2.50) 0.122(3.10) 0.114(2.90) 0.187(4.75) 0.062(1.58) 0.199(5.05) 0.122(3.10) 0.074(1.88) PIN 1 ID (NOTE 5) **Exposed Pad** 0.010(0.25) 0.0256(0.65)BSC 0.014(0.35) **BOTTOM VIEW TOP VIEW**



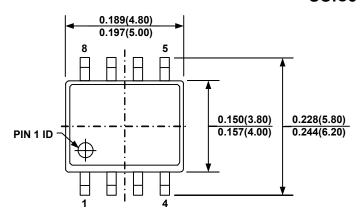


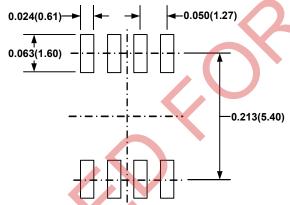
NOTE:

- 1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
- PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURR.
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) PIN 1 IDENTIFICATION HAS HALF OR FULL CIRCLE OPTION.
- 6) DRAWING MEETS JEDEC MO-187, VARIATION AA-T.
- 7) DRAWING IS NOT TO SCALE.

RECOMMENDED LAND PATTERN

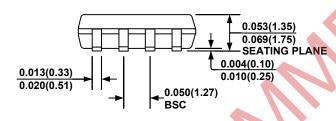
SOIC8



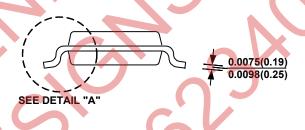


TOP VIEW

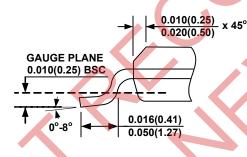
RECOMMENDED LAND PATTERN



FRONT VIEW



SIDE VIEW



DETAIL "A"

NOTE:

- 1) CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
- 2) PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 3) PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
- 4) LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
- 5) DRAWING CONFORMS TO JEDEC MS-012, VARIATION AA.
- 6) DRAWING IS NOT TO SCALE.

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